

# IGBT Module

## Sixpack

Short Circuit SOA Capability  
Square RBSOA

$$I_{C25} = 80 \text{ A}$$

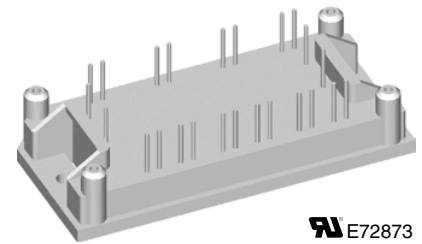
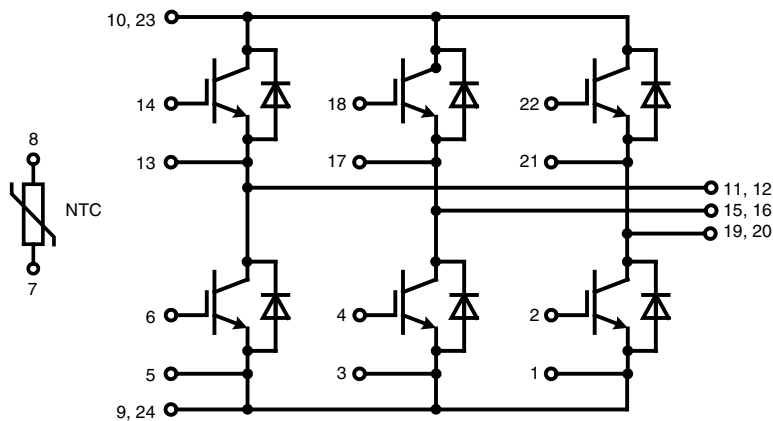
$$V_{CES} = 1200 \text{ V}$$

$$V_{CE(sat) \text{ typ.}} = 2.0 \text{ V}$$

Preliminary data

**Part name** (Marking on product)

MWI 80-12T6K



E72873

Pin configuration see outlines.

### Features:

- Trench IGBTs
  - low saturation voltage
  - positive temperature coefficient for easy paralleling
  - fast switching
  - short tail current for optimized performance also in resonant circuits
- HiPerFRED™ diode:
  - fast reverse recovery
  - low operating forward voltage
  - low leakage current
- Industry Standard Package
  - solderable pins for PCB mounting
  - isolated copper base plate

### Application:

- AC drives
- UPS
- Welding

### Package:

- UL registered
- Industry standard E1-pack

## IGBTs

Symbol	Definitions	Conditions	Ratings			Unit		
			min.	typ.	max.			
$V_{CES}$	collector emitter voltage		$T_{VJ} = 25^{\circ}\text{C}$ to $150^{\circ}\text{C}$			V		
$V_{GES}$	max. DC gate voltage	continuous			$\pm 20$	V		
$V_{GEM}$	max. transient collector gate voltage	transient			$\pm 30$	V		
$I_{C25}$	collector current		$T_C = 25^{\circ}\text{C}$			80	A	
$I_{C80}$			$T_C = 80^{\circ}\text{C}$			56	A	
$P_{tot}$	total power dissipation		$T_C = 25^{\circ}\text{C}$			270	W	
$V_{CE(sat)}$	collector emitter saturation voltage	$I_C = 50\text{ A}; V_{GE} = 15\text{ V}$	$T_{VJ} = 25^{\circ}\text{C}$			2.0	V	
			$T_{VJ} = 125^{\circ}\text{C}$			2.3	V	
$V_{GE(th)}$	gate emitter threshold voltage	$I_C = 2\text{ mA}; V_{GE} = V_{CE}$	$T_{VJ} = 25^{\circ}\text{C}$	4.5		6.5	V	
$I_{CES}$	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0\text{ V}$	$T_{VJ} = 25^{\circ}\text{C}$			0.8	1	mA
			$T_{VJ} = 125^{\circ}\text{C}$				1	mA
$I_{GES}$	gate emitter leakage current	$V_{CE} = 0\text{ V}; V_{GE} = \pm 20\text{ V}$				400	nA	
$C_{ies}$	input capacitance	$V_{CE} = 25\text{ V}; V_{GE} = 0\text{ V}; f = 1\text{ MHz}$				3600		pF
$Q_{G(on)}$	total gate charge	$V_{CE} = 600\text{ V}; V_{GE} = 15\text{ V}; I_C = 50\text{ A}$				470		nC
$t_{d(on)}$	turn-on delay time	} inductive load $V_{CE} = 600\text{ V}; I_C = 50\text{ A}$ $V_{GE} = \pm 15\text{ V}; R_G = 18\ \Omega$	$T_{VJ} = 125^{\circ}\text{C}$			90		ns
$t_r$	current rise time					50		ns
$t_{d(off)}$	turn-off delay time					520		ns
$t_f$	current fall time					90		ns
$E_{on}$	turn-on energy per pulse					5		mJ
$E_{off}$	turn-off energy per pulse					6.5		mJ
$I_{CM}$	reverse bias safe operating area	RBSOA; $V_{GE} = \pm 15\text{ V}; R_G = 18\ \Omega$ $L = 100\ \mu\text{H};$ clamped induct. load $V_{CEmax} = V_{CES} - L_S \cdot di/dt$	$T_{VJ} = 125^{\circ}\text{C}$			100		A
$t_{SC}$ (SCSOA)	short circuit safe operating area	$V_{CE} = 900\text{ V}; V_{GE} = \pm 15\text{ V};$ $R_G = 18\ \Omega;$ non-repetitive	$T_{VJ} = 125^{\circ}\text{C}$			10		$\mu\text{s}$
$R_{thJC}$	thermal resistance junction to case	(per IGBT)				0.46		K/W
$R_{thCH}$	thermal resistance case to heatsink	(per IGBT)				0.2		K/W

## Diodes

Symbol	Definitions	Conditions	Maximum Ratings				
			min.	typ.	max.		
$V_{RRM}$	max. repetitive reverse voltage				1200	V	
$I_{F25}$	forward current		$T_C = 25^{\circ}\text{C}$			80	A
$I_{F80}$			$T_C = 80^{\circ}\text{C}$			51	A

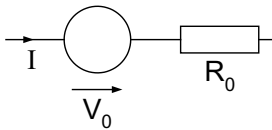
Symbol	Conditions	Characteristic Values					
		min.	typ.	max.			
$V_F$	forward voltage	$I_F = 50\text{ A}$					
		$T_{VJ} = 25^{\circ}\text{C}$			2.3	V	
		$T_{VJ} = 125^{\circ}\text{C}$			1.6	V	
$I_{RM}$	max. reverse recovery current	} $V_R = 600\text{ V}; I_F = 50\text{ A}$ $di_F/dt = -600\text{ A}/\mu\text{s}$	$T_{VJ} = 100^{\circ}\text{C}$			35	A
$t_{rr}$	reverse recovery time		$T_{VJ} = 100^{\circ}\text{C}$			200	ns
$R_{thJC}$	thermal resistance junction to case	(per diode)	$T_{VJ} = 25^{\circ}\text{C}$			0.65	K/W
$R_{thCH}$	thermal resistance case to heatsink	(per diode)			0.25	K/W	

**Temperature Sensor NTC**

Symbol	Definitions	Conditions	Ratings			Unit
			min.	typ.	max.	
$R_{25}$	<i>resistance</i>	$T_C = 25^\circ\text{C}$	4.45	4.7	5.0	k $\Omega$
$B_{25/85}$				3510		K

**Module**

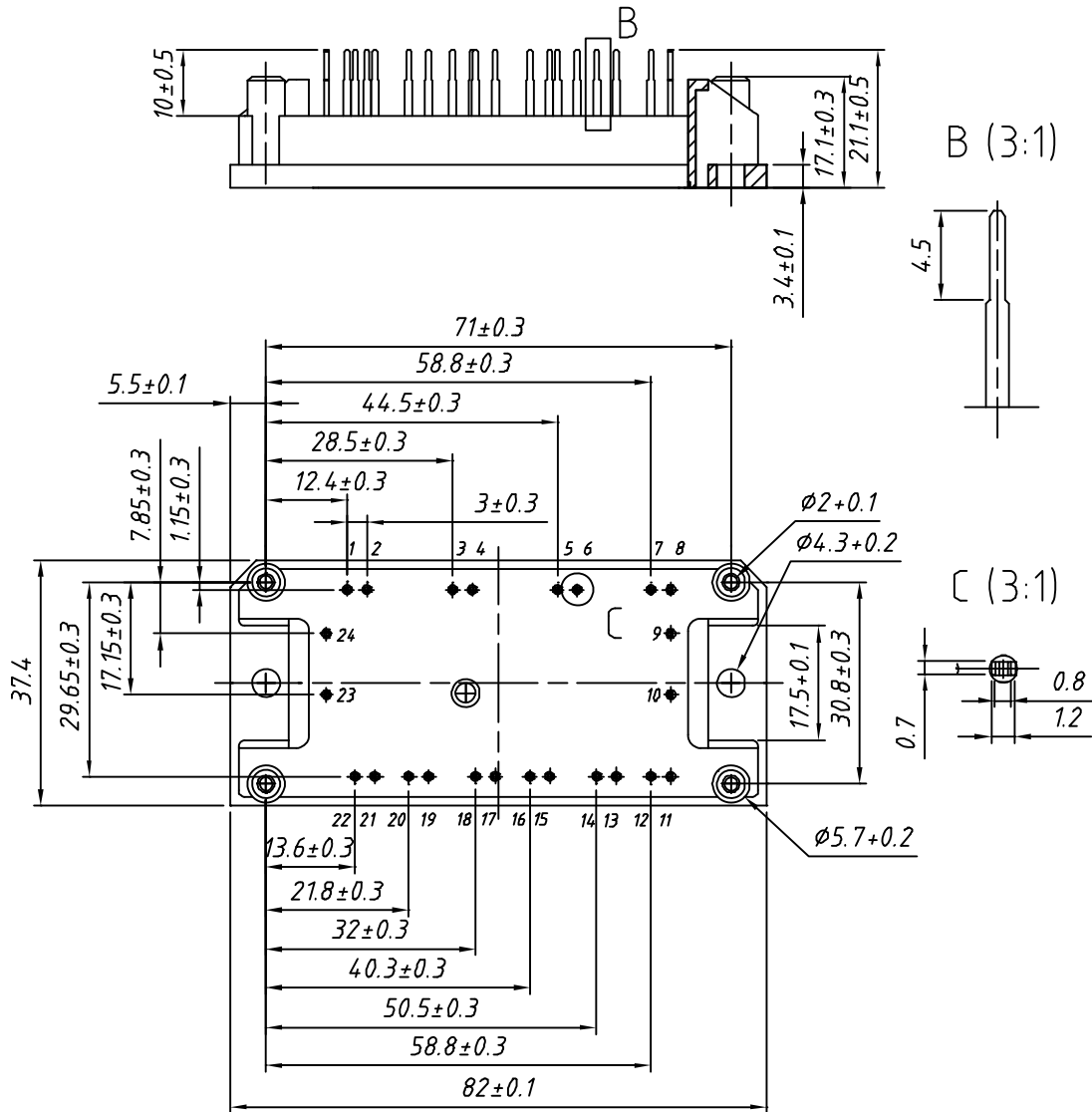
Symbol	Definitions	Conditions	Ratings			Unit
			min.	typ.	max.	
$T_{VJ}$	<i>operating temperature</i>		-40		125	$^\circ\text{C}$
$T_{VJM}$	<i>max. virtual junction temperature</i>				150	$^\circ\text{C}$
$T_{stg}$	<i>storage temperature</i>		-40		125	$^\circ\text{C}$
$V_{ISOL}$	<i>isolation voltage</i>	$I_{ISOL} \leq 1 \text{ mA}; 50/60 \text{ Hz}$			2500	V~
$M_d$	<i>mounting torque</i>	(M4)	2.0		2.2	Nm
$d_S$	<i>creep distance on surface</i>		12.7			mm
$d_A$	<i>strike distance through air</i>		12.7			mm
<b>Weight</b>				40		g

**Equivalent Circuits for Simulation**

**Ratings**

Symbol	Definitions	Conditions	min.	typ.	max.	Unit
$V_0$	<i>IGBT</i>	$T_{VJ} = 125^\circ\text{C}$		tbd		V
$R_0$				tbd		m $\Omega$
$V_0$	<i>free wheeling diode</i>	$T_{VJ} = 125^\circ\text{C}$		1.5		V
$R_0$				6		m $\Omega$

## Outline Drawing

Dimensions in mm (1 mm = 0.0394")



## Product Marking

Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Ordering Code
Standard	MWI 80-12T6K	MWI80-12T6K	Box	10	500 159